





















Photovoltaics Fabrication



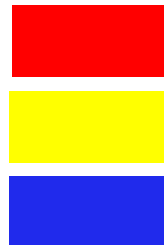
Date	Bay	Process	Device cross section
	Wet etch	RCA	
	Diffusion	Pyrogenic oxidation	
	Inline characterisation	Inspection: Oxide thickness measurement	
	Lithography	Optical lithography (Pattern definition)	
	Lithography	Inspection: Microscope imaging	
	Wet etch	PR strip	
	Wet etch	RCA	

	Diffusion	Phosphorous diffusion	
	Wet etch	PSG removal	
	Inline characterisation	Sheet resistance measurement (dummy wafer)	
	Thin films	Al deposition	
	Lithography	For metal contacts	
	Lithography	Inspection: Microscope imaging	
	Wet etch	Al etch	
	Lithography	Inspection: Microscope imaging	
	Wet etch	PR strip	
	Lithography	Front PR coating	

	Wet etch	Back SiO ₂ Etch	
	Lithography	PR strip	
	Thin films	Back side Al deposition	
	Furnaces	Annealing	



Silicon
Oxide
PSG



Photoresist
Diffusion
Metal